

Title (en)

Continuous molded electronic component assembly

Title (de)

Anordnung von kontinuierlich eingebetteten elektronischen Bauelementen

Title (fr)

Assemblage de composants électroniques moulés de façon continue

Publication

**EP 0418993 B1 19960117 (EN)**

Application

**EP 90302433 A 19900307**

Priority

US 40952489 A 19890919

Abstract (en)

[origin: EP0418993A2] A continuous molded electronic component assembly process in which a continuous line of components (17) are supplied on reels (20,21) for assembly and insertion is described. The supply reels (20) of electronic components are made by an injection molding process, reeled and supplied to assembly and insertion machines. The assembly and insertion machines provide the means for removing, assembling and inserting the electronic components. Examples of the process, but not limited to, are shunts, wire end terminals and pilot posts.

IPC 1-7

**H01R 43/24**; **H01R 43/20**; **H01R 23/72**; **H05K 13/04**

IPC 8 full level

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